



DESCRIPTION

DO-214AC/SMA Thyristor solid state protection thyristor protect telecommunications equipment such as modems, line cards, fax machines, and other CPE. This Series devices are used to enable equipment to meet various regulatory requirements including GR-1089, ITUK.20, K.21 and K.45, IEC 60950, and TIA-968 (formerly known as FCC Part 68).

FEATURES

- ◆ Excellent capability of absorbing transient surge
- ◆ Quick response to surge voltage
- ◆ Eliminates overvoltage caused by fast rising transients
- ◆ Solid-state silicon technology, non degenerative

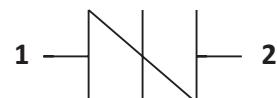
APPLICATIONS

- ◆ Audio/Video line
- ◆ Network and telecom
- ◆ Data lines and security systems
- ◆ Serial ports

DO-214AC PACKAGE



SCHEMATIC SYMBOL



PART NUMBER AND ELECTRICAL PARAMETER @ T=25°C RH = 45%-75%

PART NUMBER	V _{DRM} V	I _{DRM} mA Max	V _s V Max	I _s mA	V _T V Max	I _T A	I _H mA Min	C ₀ pF Typ
P0080TA	6	5	25	800	4	2.2	50	50
P0300TA	25	5	40	800	4	2.2	50	50
P0640TA	58	5	77	800	4	2.2	50	50
P1800TA	170	5	220	800	4	2.2	50	50
P2300TA	190	5	260	800	4	2.2	50	50
P2600TA	220	5	300	800	4	2.2	50	50
P3100TA	275	5	350	800	4	2.2	50	50
P3500TA	320	5	400	800	4	2.2	50	50
P4200TA	390	5	500	800	4	2.2	50	50

1、Vs is measured at 100KV/us

2、Off-state capacitance is measured in V_{DC}=2V, V_{RMS}=1V, F=1MHz

3、All measurements are made at an ambient temperature of 25°C

SURGE RATINGS

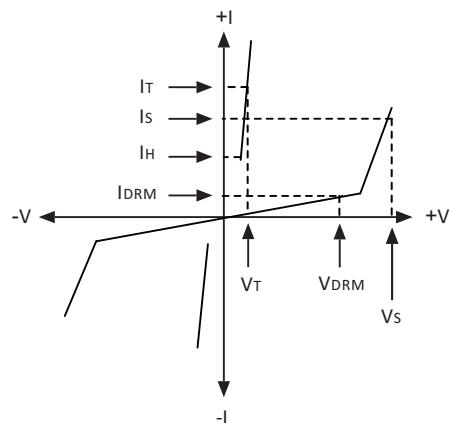
Series	IPP 2x10us (A)	IPP 8x20us (A)	IPP 10x560us (A)	IPP 10x1000us (A)	VPP 10x700us (V)	I _{TSM} 60Hz (A)	d _i /d _t (A/us)
P0080TA Thru P4200TA	150	150	50	45	3000	20	500



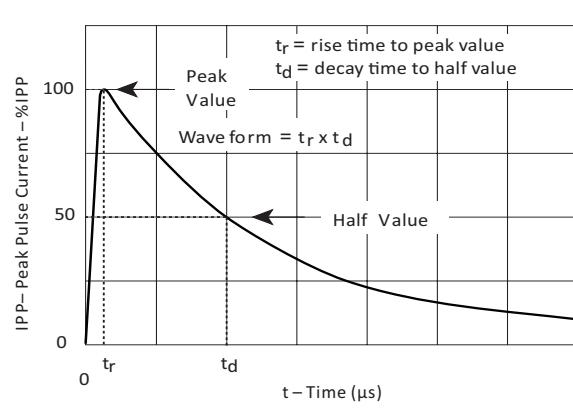
THERMAL CONSIDERATIONS

Symbol	Parameter	Value	Unit
T_J	Operating Junction Temperature	-40 to +150	°C
T_S	Storage Temperature Range	-40 to +150	°C
$R_{\theta JA}$	Junction to Ambient on printed circuit	90	°C/W

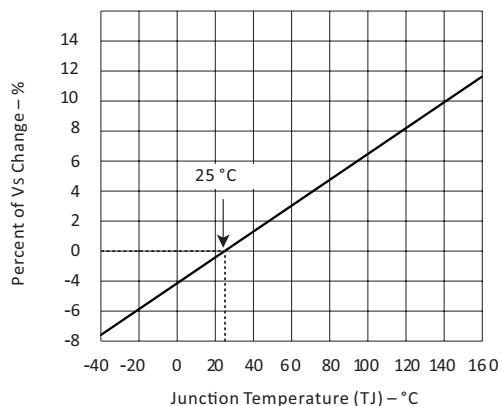
TYPICAL DEVICE CHARACTERISTICS



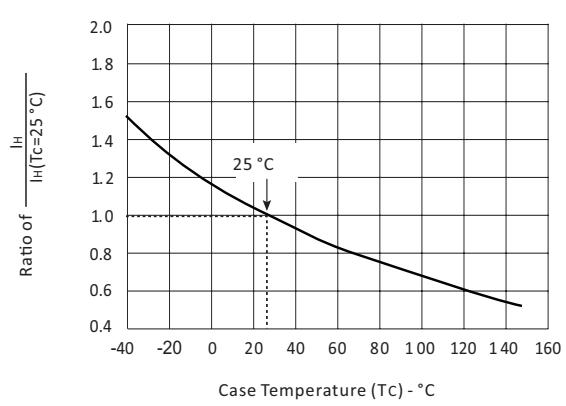
V-I Characteristics



tr x td Pulse Waveform



Normalized V_s Change vs. Junction Temperature



Normalized DC Holding Current vs. Case Temperature



ENVIRONMENTAL CHARACTERISTICS

Testing Items	Technical Standards
High Temperature Reverse Bias Test	Temperature:150±3°C,Bias=80%V _{DRM} ;Time:168H
High Temperature Life Test	Temperature:150°C ;Time:168H
High-Low Temperature Cycle Test	Temperature:From -40°C to 150°C ;Dwell Time:30min,10-100 Cycles
High Temperature&High Humidity Test	Temperature:85°C.Humidity:85%; Time:168H
Pressure Cooker Test	Temperature:121°C,2 atm.Humidity:100%; Time:24H To 168H
Resistance Of Soldering Heat	Temperature:260±5°C;Time Of Dip Soldering:10s,3 Times

PRODUCT DIMENSIONS

OUTLINE DIMENSIONS				
DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	1.23	1.63	0.049	0.064
B	4.10	4.55	0.162	0.179
C	2.51	2.76	0.099	0.109
D	1.96	2.26	0.077	0.089
E	0.75	1.51	0.030	0.060
F	0.00	0.20	0.000	0.008
G	4.87	5.22	0.192	0.206
H	0.15	0.30	0.006	0.012

NOTES

1. Dimensions are exclusive of mold flash and metal burrs.

RECOMMENDED PAD LAYOUT DIMENSIONS

PAD LAYOUT DIMENSIONS				
DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	1.57	-	0.062	-
B	1.55	-	0.061	-
C	-	2.28	-	0.090
D	1.55	-	0.061	-